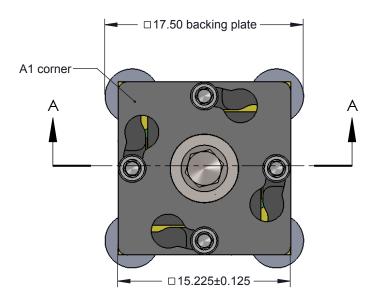
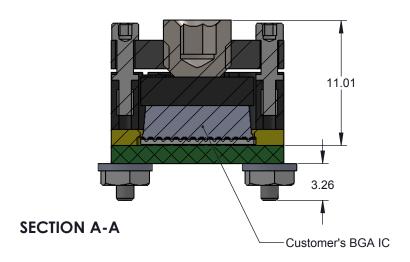
Swivel Lid socket - Silver ball matrix interconnect- Direct mount, solderless

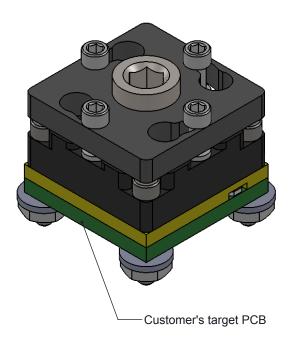


TOP VIEW



Features

- Direct mounts to target PCB with hardware. High speed, reliable connection
- Minimum real estate required
- Easily removalbe swivel socket lid



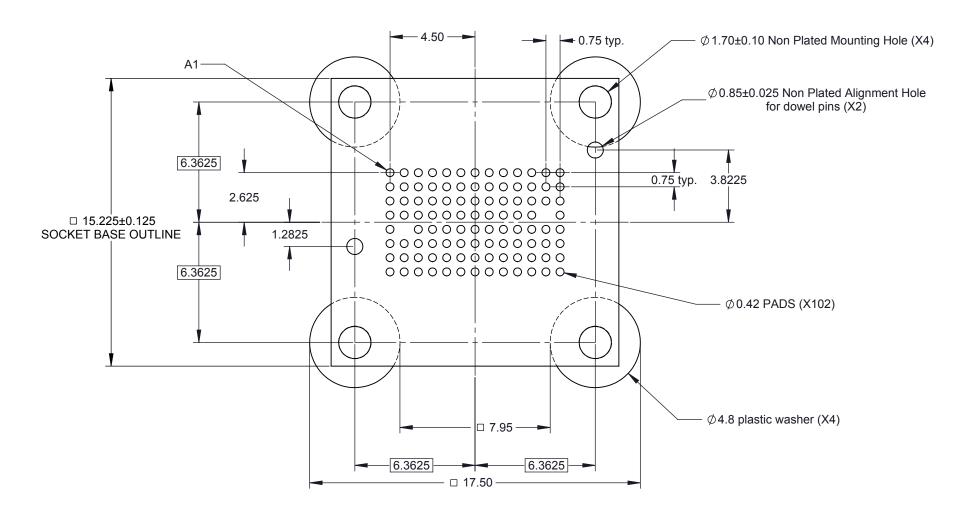
Description: SM socket for 9.75x6mm, 13x8 0.75mm pitch BGA102

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9007 Drawing	Inc. Finish: N/A Weight: 6.53	STATUS: Released	SHEET: 1 OF 4	REV. B
Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: E. Smolentseva	DRAWN BY: E. Smolentseva	SCALE: 3:1
www.ironwoodelectronics.com		FILE: SM-BGA-9007 Dwg	DATE: 2/10/2012	

Recommended PCB Layout



<u>Target PCB Recommendations</u> Total thickness: 0.864mm min.

Plating: Gold or Solder finish
PCB Pad height: same or higher than solder mask

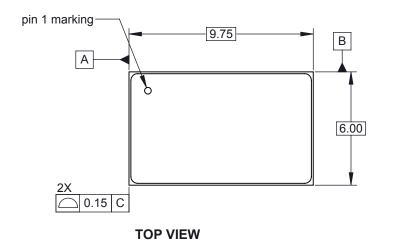
Description: SM socket for 9.75x6mm, 13x8 0.75mm pitch BGA102

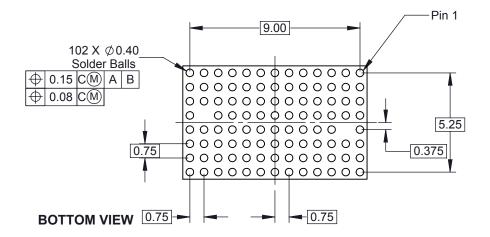
Primary dimension units are millimeters, Secondary dimension units are [inches].

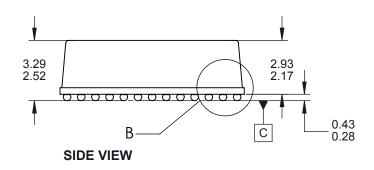
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

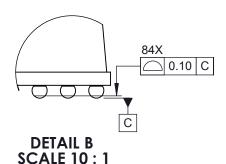
SM-BGA-9007 Specification	SM-BGA-9007 Specification Material: N/A		SHEET: 2 OF 4	REV. B
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 6.53	DRAWN BY: E. Smolentseva	SCALE: 5:1	
		FILE: SM-BGA-9007 Dwg	DATE: 2/10/2012	

Compatible BGA IC









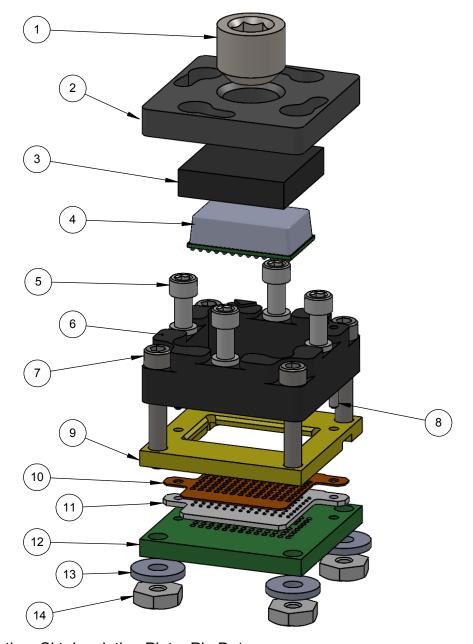
- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: IC package

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SM-BGA-9007 Drawing Material: N/A		STATUS: Released	SHEET: 3 OF 4	REV. B
©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 6.53	ENG: E. Smolentseva	DRAWN BY: E. Smolentseva	SCALE: 5:1	
			FILE: SM-BGA-9007 Dwg	DATE: 2/10/2012	



ITEM NO.	DESCRIPTION	Material
1	Compression Screw M6x1	Stainless Steel (18-8)
2	Socket Lid	7075-T6 Aluminum Alloy
3	Compression Plate	7075-T6 Aluminum Alloy
4	test chip	Material <not specified=""></not>
5	#0-80 Shoulder Screw, 2.29mm thread length	Stainless Steel (303)
6	Socket Base	7075-T6 Aluminum Alloy
7	#0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
8	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
9	IC guide	Torlon 4203
10	BGA ball guide	Kapton Polyimide/Cirlex
11	SM interposer	Silmat
12	test pcb	FR4 High temp
13	Washer, #0 x .025", Nylon	Nylon 6/6
14	Nut, #0-80, SS	Stainless Steel (18-8)

Description: Skt, Insulation Plate, Pin Det

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Rev	Date	Initials	Description
Α	02/10/12	ELS	Original
В	07/23/15	DH	Changed IC g=Guide material from Ultem to Torlon

SM	I-BGA	-9007	Draw	/ing



©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: N/A Finish: N/A Weight: 6.53

STATUS: Released	SHEET: 4 OF 4	REV. B
ENG: E. Smolentseva	DRAWN BY: E. Smolentseva	SCALE: 3:1
FILE: SM-BGA-9007 Dwg	DATE: 2/10/2012	